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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

Cautions

Keep safety first in your circuit designs!

1. Renesas Technology Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage.

Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HSD88

Silicon Schottky Barrier Diode for Various Detector, Mixer



ADE-208-1386 (Z)

Rev.0
Jun. 2001

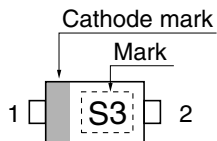
Features

- Low capacitance. (C = 0.8 pF max)
- Low forward voltage.
- Super small Flat Package (SFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HSD88	S3	SFP

Pin Arrangement



1. Cathode
2. Anode

Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V_R	10	V
Average rectified current	I_O	15	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	–55 to +125	°C

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_{F1}	350	—	420	mV	$I_F = 1 \text{ mA}$
	V_{F2}	500	—	580		$I_F = 10 \text{ mA}$
Reverse current	I_{R1}	—	—	0.2	μA	$V_R = 2 \text{ V}$
	I_{R2}	—	—	10		$V_R = 10 \text{ V}$
Capacitance	C	—	—	0.8	pF	$V_R = 0 \text{ V}$, $f = 1 \text{ MHz}$
ESD-Capability ^{*1}	—	30	—	—	V	C = 200 pF, R = 0 Ω , Both forward and reverse direction 1 pulse.

Notes: 1. Failure criterion ; $I_R > 0.4 \mu\text{A}$ at $V_R = 2 \text{ V}$

2. Please do not use the soldering iron due to avoid high stress to the SFP package.

Main Characteristic

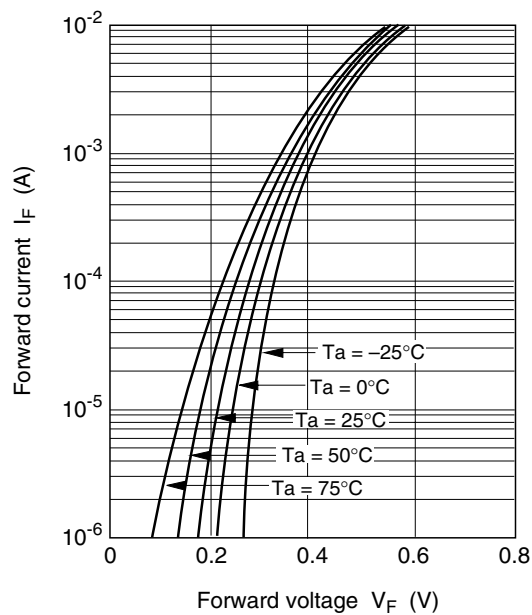


Fig.1 Forward current vs. Forward voltage

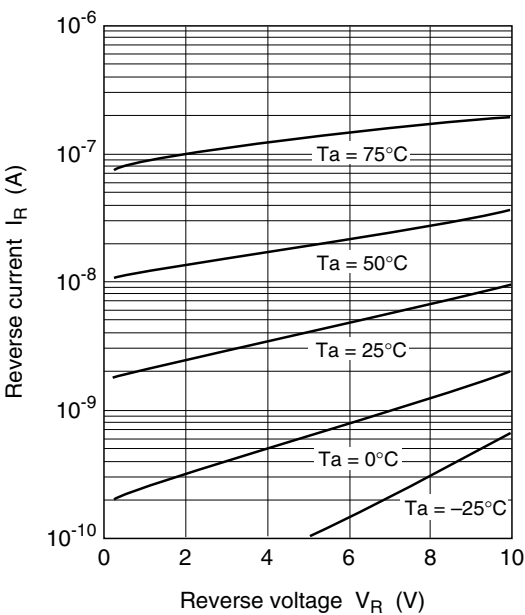


Fig.2 Reverse current vs. Reverse voltage

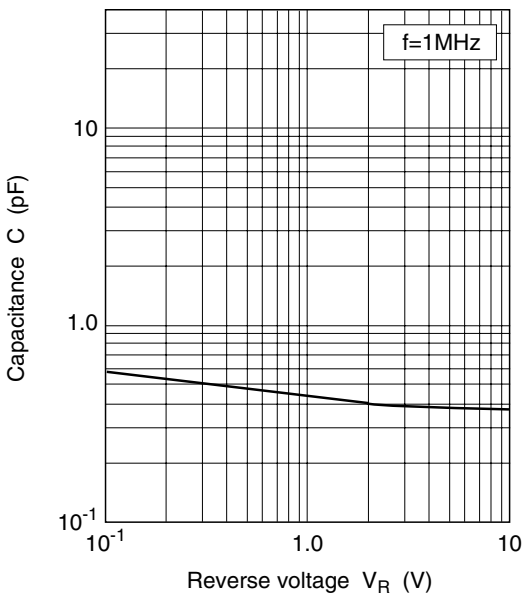
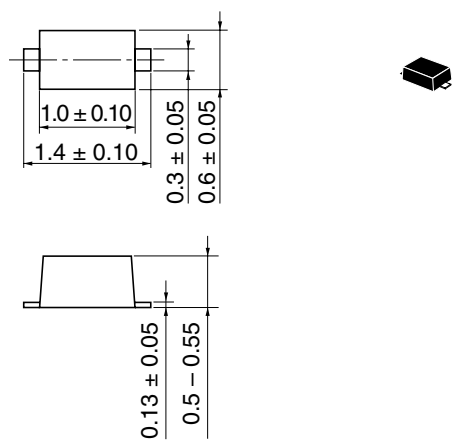


Fig.3 Capacitance vs. Reverse voltage

Package Dimensions

As of January, 2001
Unit: mm



Hitachi Code	SFP
JEDEC	—
EIAJ	—
Mass (reference value)	0.0010 g

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